

## RTE Food Packaging Seminar

### UV & EB-Printing for Food Packaging

25 October, Mövenpick Airport Hotel, Stuttgart



Find out how your company can benefit from the fast-curing, high-quality and low-VOC food packaging printing offered by UV/EB and UV-LED in a convenient one-day seminar.

Meet the leading industry experts in materials, inks, printing, equipment and packaging, and regulatory affairs for the radiation curing industry.

This event is your chance to learn about all aspects of UV/EB and UV-LED for food packaging:

- The latest technological developments
- The current and expected regulatory requirements
- The vision of customers and brand-owners
- Real-life examples of the application of the technology for food packaging products

## Programme

### 24 October 2018

**13:00 – 17:00** RadTech Europe General Assembly (*members only*)

**20:00 – 22:00** Optional networking dinner

### 25 October 2018

**08.45 – 09.15** Reception and registration

**09.15 – 09.30** Welcome & Short introduction to the program – Mark Macaré, RadTech Europe

#### **Session A: Introduction to the technology**

**09.30 – 10.00** Chemistry – Luc de Waele, Allnex

A comprehensive overview will be given in applied chemistries in printing and packaging materials. Focus will be on state of the art radiation curing systems. Trends for new development will be highlighted.

**10.00 – 10.30** View from a converter on the safe use of UV and EB technology – Manfred Hoffman, Amcor

A view from a converter on the Product Safety aspects of UV and EB printed materials.

**10.30 – 11.00** Coffee break

**11.00 – 11.30** Brand owner perspective, Amaury Patin, Nestlé

A view of a major brand owner on the position of Radcure in printing and packaging and the future outlook in the packaging industry in respect to safety and sustainability. This will also include an explanation of the legal regulations in relation to the brand owner specifications.

#### **Session B: Chairman session on curing technologies**

**11.30 – 12.15** Interactive Q&A session – representatives from Efsen Engineering, Phoseon, Energy Sciences Inc. and Heraeus Noblelight

Panel discussion with focus on developments in UV, EB & UV LED curing technology for low migration applications in food packaging, and inline monitoring equipment.

**12.15 – 13.15** Lunch

#### **Session C: Legislation & testing: status; opportunities and threats**

**13.15 – 13.45** Developments in European Food Contact Legislation, Martin Klatt, BASF and RTE HSE Chairman

A short overview of European Food Contact Legislation will be given, including the practical data requirements and developments in the legislation.

**13.45 – 14:15** Safe use of radiation cured inks and varnishes – European Printing Inks Association

Viewpoint of the printing ink industry on the usage of radiation cured product in the various applications.

- 14.15 – 15.15 Q/A session on food contact legislation**  
 Panel discussion with a focus on the developments in and impact of food contact legislation for the entire supply chain.
- 15.15 – 15.45 Coffee break**
- Session D: Application technology**
- 15.45 – 16.15 Advantages of UV Flexo – Federico D’Annunzio, Bobst**  
 Insight into the benefits of UV flexo vs conventional printing technologies.
- 16.15 – 16.45 Developments in radiation curing for inkjet: A holistic approach to uv inkjet – Steve Knight, Digital Direct/TheIJC**  
 Achieving full cure requires much more than inkjet chemistry and UV radiation. From software to printhead calibration every element of inkjet engineering and inkjet chemistry impacts curing. Consideration of the total system is require to ensure consistent and repeatable results.
- 16.45 – 17.15 The UVFoodSafe initiative – FINAT, Jonathan Sexton**  
 An introduction of the new industry initiative to expand the confidence in the use of UV printing in food packaging and labels.
- 17.15 – 18.00 Conclusion and opening the opportunity for networking and discussion**  
 Small snack and drink to ease the networking activities with the participants and speakers

*Language: English*

## Information and general conditions

### Participation fee

- RadTech Europe members: € 270,-
- Non RadTech Europe members: € 330,-
- End-users € 300,-

*\*registrations received before the 15<sup>th</sup> of July are offered a 10% discount*

*\* Excluding German VAT (RTE is obliged to charge the VAT of the country where the event is taking place).*

**Registration:** <https://lejeune131.typeform.com/to/i87cLp>

### Cancellation policy

Full refund registration fee will be granted if the cancellation is received in writing before 15 September 2018. No refunds will be granted for cancellations received after 15 September 2018. Cancellations by telephone will not be accepted.

### Hotel recommendation

Hotel reservations can be made via the RTE Secretariat ([mail@radtech-europe.com](mailto:mail@radtech-europe.com)).

### Venue

Mövenpick Hotel Stuttgart  
 AirportFlughafenstrasse 50  
 70629 Stuttgart  
 Germany

